



EE141-Fall 2004 Digital Integrated Circuits

Lecture 19
Pass-Transistor Logic
Dynamic Logic

EECS141

Administrative Stuff

- Homework #8 due the Spring break
- Project phase 2 due on Monday
 - Report template posted on the web
 - Reports due after Spring break
- Midterm 2 coming up
 - Thursday, April 6, 6:30-8pm, 277 Cory

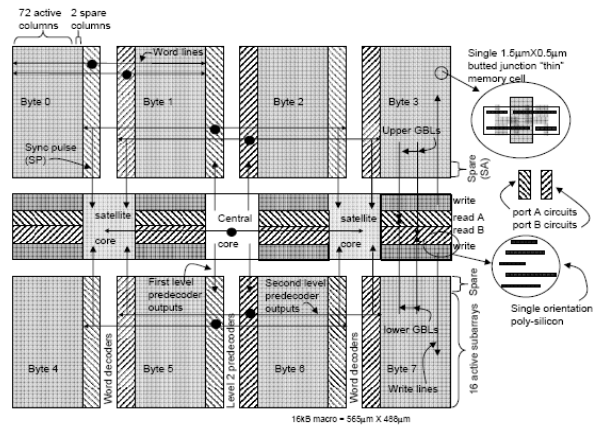
EECS141

Class Material

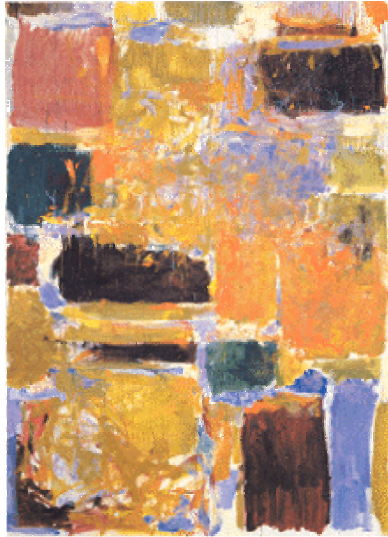
- Last lecture
 - Decoder design
 - Pass-transistor logic
- Today's lecture
 - Finish pass-transistor logic
 - Dynamic logic
- Reading
 - Chapter 6

EECS141

Practical SRAM Design



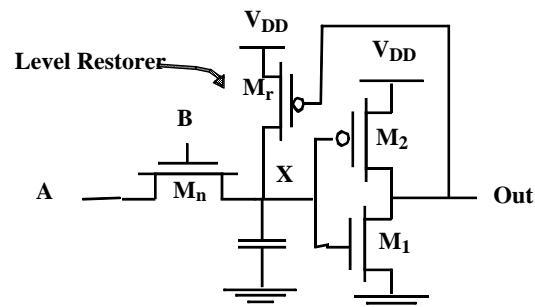
EECS141



Pass-Transistor Logic

EECS141

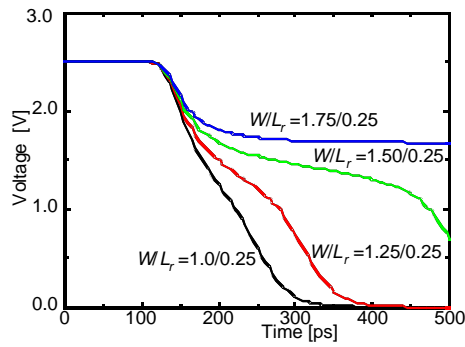
NMOS Only Logic: Level Restoring Transistor



- Advantage: Full Swing
- Restorer adds capacitance, takes away pull down current at X
- Ratio problem

EECS141

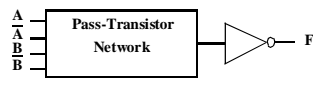
Restorer Sizing



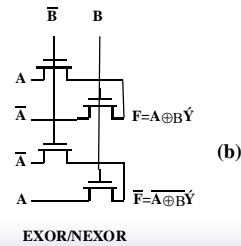
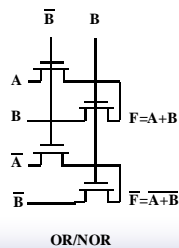
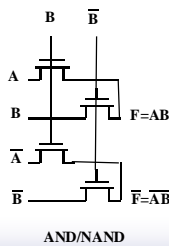
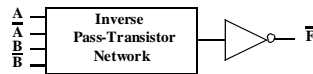
- Upper limit on restorer size
- Pass-transistor pull-down can have several transistors in stack

EECS141

Complementary Pass Transistor Logic



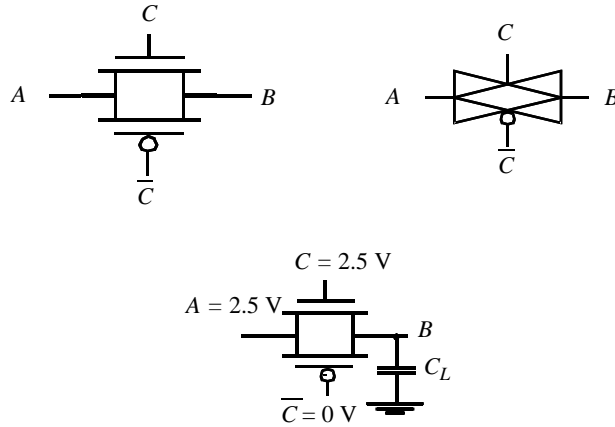
(a)



(b)

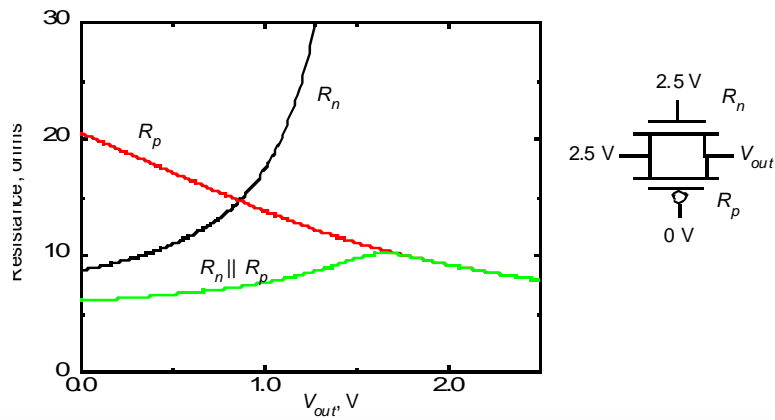
EECS141

Solution 2: Transmission Gate



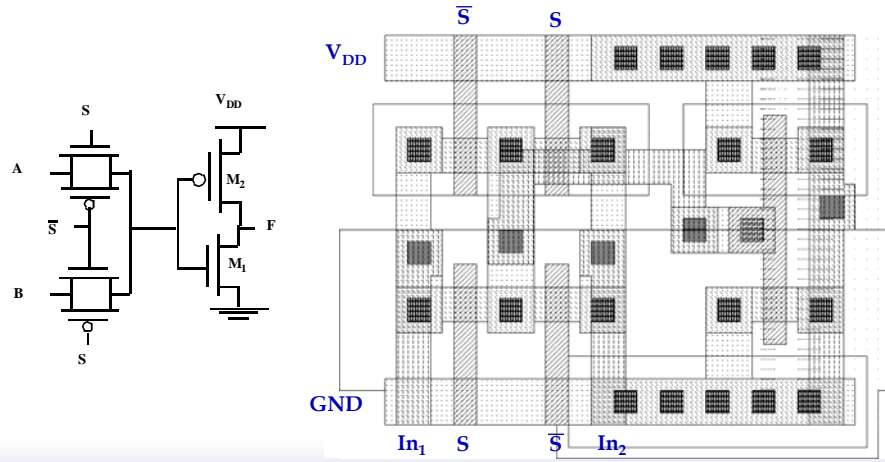
EECS141

Resistance of Transmission Gate



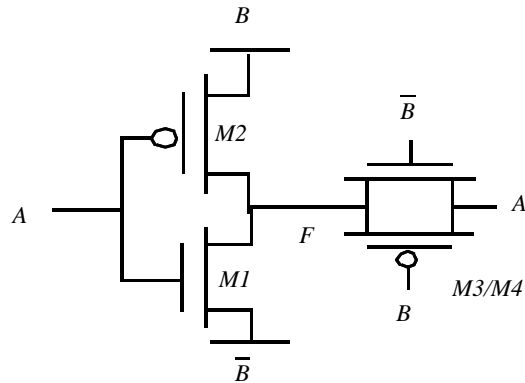
EECS141

Pass-Transistor Based Multiplexer



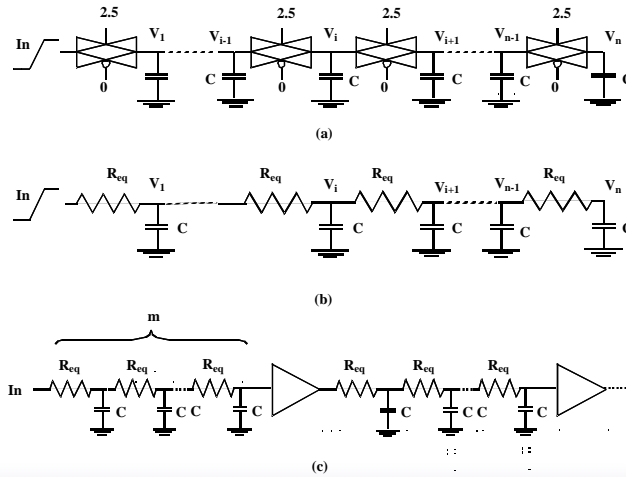
EECS141

Transmission Gate XOR



EECS141

Delay in Transmission Gate Networks



EECS141

Delay Optimization

- Delay of RC chain

$$t_p = 0.69 \sum_{k=0}^{n-1} CR_{eq}^k = 0.69 CR_{eq} \frac{n(n+1)}{2}$$

- Delay of Buffered Chain

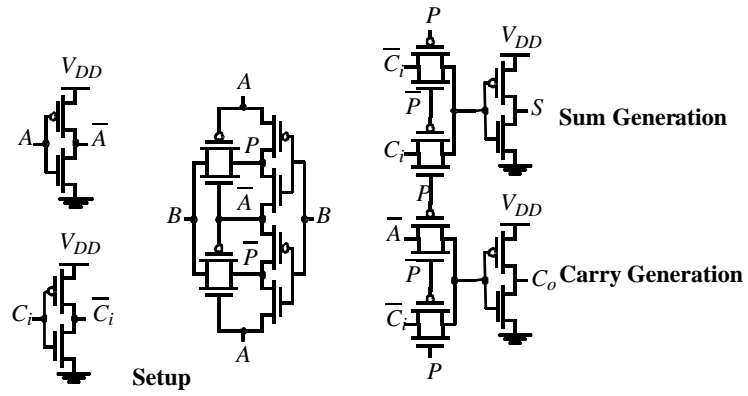
$$t_p = 0.69 \left[\frac{n}{m} CR_{eq} \frac{m(m+1)}{2} \right] + \left(\frac{n}{m} - 1 \right) t_{buf}$$

$$= 0.69 \left[CR_{eq} \frac{n(m+1)}{2} \right] + \left(\frac{n}{m} - 1 \right) t_{buf}$$

$$m_{opt} = 1.7 \sqrt{\frac{t_{buf}}{CR_{eq}}}$$

EECS141

Transmission Gate Full Adder



Similar delays for sum and carry

EECS141



Dynamic Logic

EECS141

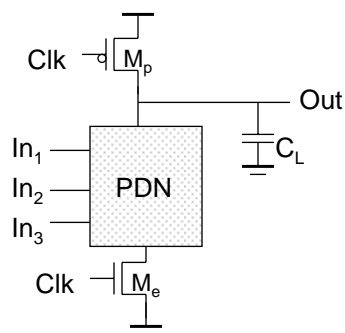
Dynamic CMOS

- In **static** circuits at every point in time (except when switching) the output is connected to either GND or V_{DD} via a low resistance path.
 - fan-in of n requires $2n$ (n N-type + n P-type) devices

- **Dynamic** circuits rely on the temporary storage of signal values on the capacitance of high impedance nodes.
 - requires on $n + 2$ ($n+1$ N-type + 1 P-type) transistors

EECS141

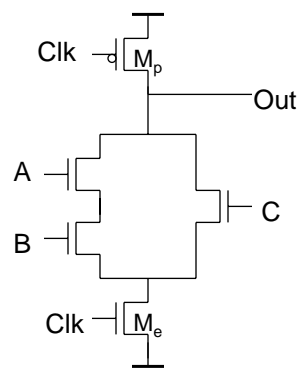
Dynamic Gate



Two phase operation

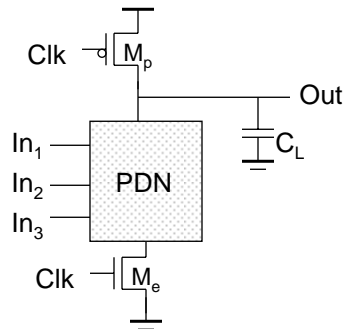
Precharge (CLK = 0)

Evaluate (CLK = 1)



EECS141

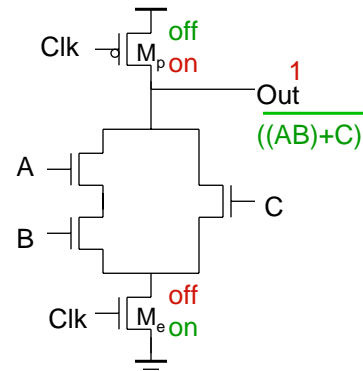
Dynamic Gate



Two phase operation

Precharge (Clk = 0)

Evaluate (Clk = 1)



EECS141

Conditions on Output

- ❑ Once the output of a dynamic gate is discharged, it cannot be charged again until the next precharge operation.
- ❑ Inputs to the gate can make **at most** one transition during evaluation.
- ❑ Output can be in the high impedance state during and after evaluation (PDN off), state is stored on C_L

EECS141

Properties of Dynamic Gates

- Logic function is implemented by the PDN only
 - number of transistors is $N + 2$ (versus $2N$ for static complementary CMOS)
- Full swing outputs ($V_{OL} = \text{GND}$ and $V_{OH} = V_{DD}$)
- Non-ratioed - sizing of the devices does not affect the logic levels
- Faster switching speeds
 - reduced load capacitance due to **lower input** capacitance (C_{in})
 - reduced load capacitance due to smaller output loading (C_{out})
 - no I_{sc} , so all the current provided by PDN goes into discharging C_L

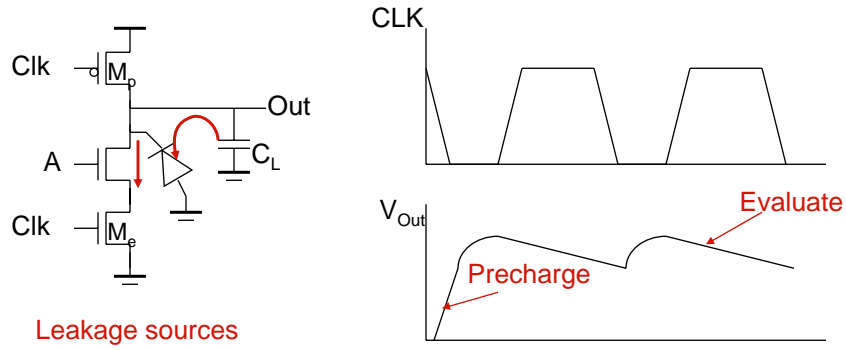
EECS141

Properties of Dynamic Gates

- Overall power dissipation usually **higher** than static CMOS
 - no static current path ever exists between V_{DD} and GND (including P_{sc})
 - no glitching
 - **higher transition probabilities**
 - **extra load on Clk**
- PDN starts to work as soon as the input signals exceed V_{Tn} , so V_M , V_{IH} and V_{IL} equal to V_{Tn}
 - low noise margin (NM_L)
- Needs a precharge/evaluate clock

EECS141

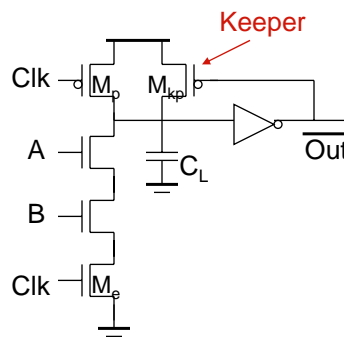
Issues in Dynamic Design 1: Charge Leakage



Dominant component is subthreshold current

EECS141

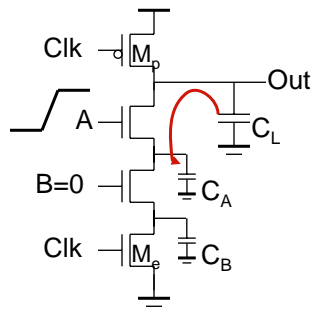
Solution to Charge Leakage



Same approach as level restorer for pass-transistor logic

EECS141

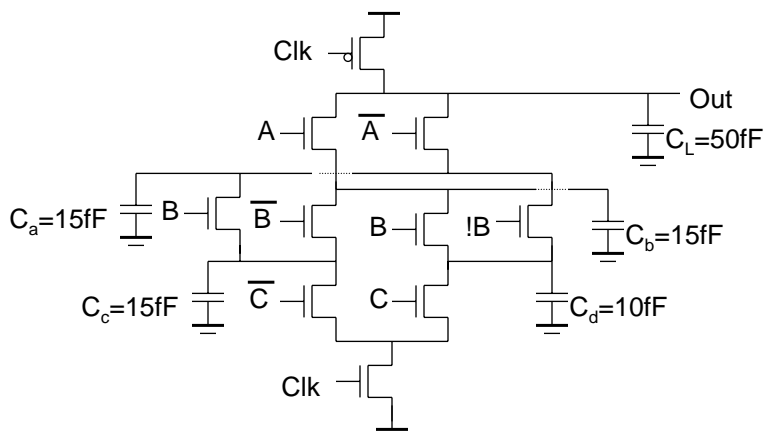
Issues in Dynamic Design 2: Charge Sharing



Charge stored originally on C_L is redistributed (shared) over C_L and C_A leading to reduced robustness

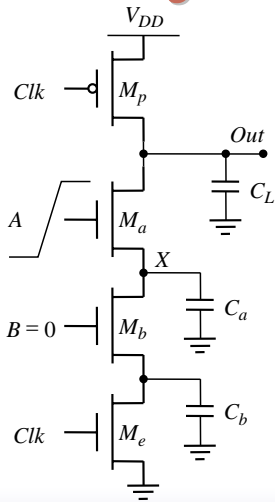
EECS141

Charge Sharing Example



EECS141

Charge Sharing



case 1) if $\Delta V_{out} < V_{Tn}$

$$C_L V_{DD} = C_L V_{out}(t) + C_a (V_{DD} - V_{Tn}(V_X))$$

or

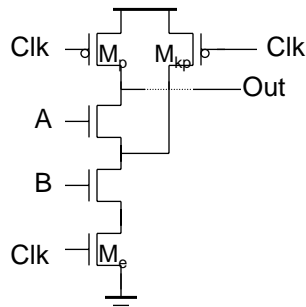
$$\Delta V_{out} = V_{out}(t) - V_{DD} = -\frac{C_a}{C_L} (V_{DD} - V_{Tn}(V_X))$$

case 2) if $\Delta V_{out} > V_{Tn}$

$$\Delta V_{out} = -V_{DD} \left(\frac{C_a}{C_a + C_L} \right)$$

EECS141

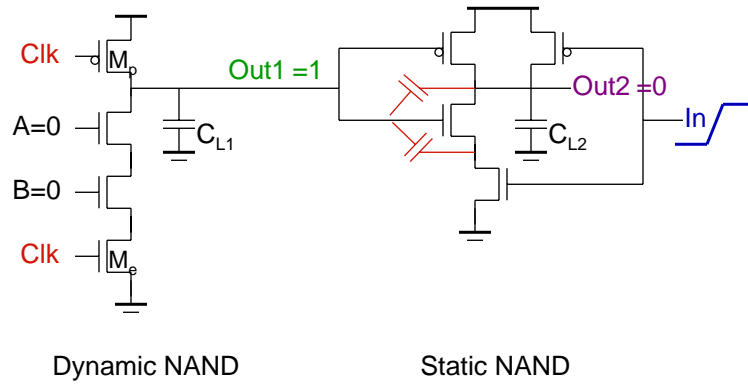
Solution to Charge Redistribution



Precharge internal nodes using a clock-driven transistor (at the cost of increased area and power)

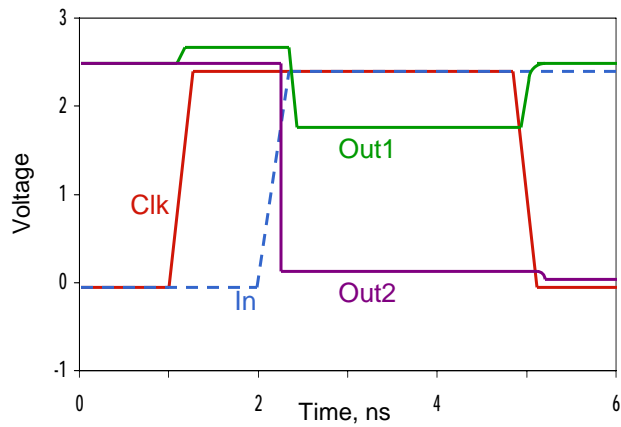
EECS141

Issues in Dynamic Design 3: Backgate Coupling



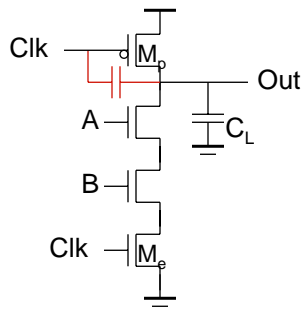
EECS141

Backgate Coupling Effect



EECS141

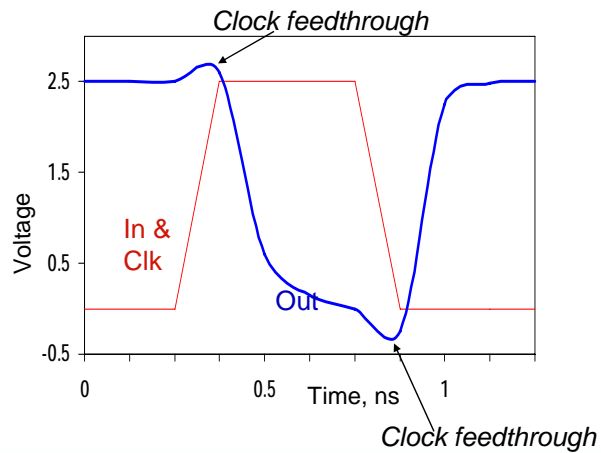
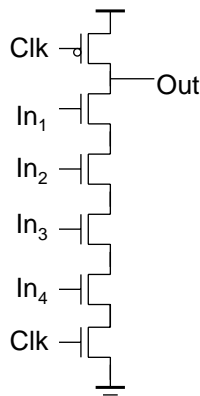
Issues in Dynamic Design 4: Clock Feedthrough



Coupling between Out and Clk input of the precharge device due to the gate to drain capacitance. So voltage of Out can rise above V_{DD} . The fast rising (and falling edges) of the clock couple to Out.

EECS141

Clock Feedthrough



EECS141

Other Effects

- Capacitive coupling
- Substrate coupling
- Minority charge injection
- Supply noise (ground bounce)

EECS141

Next Lecture

- Finish dynamic logic
 - Domino logic
- Digital arithmetic
 - Datapath design
 - Adders

EECS141